

L Number	Hits	Search Text	DB	Time stamp
1	2	6519842.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/16 08:19
2	24	("4333966" "4401767" "4436785" "4459166" "4463030" "4652465" "4670188" "4749120" "4855102" "4859241" "5194128" "5196371" "5286927" "5477419" "5714252" "5832595" "5860212" "5882722" "5918364" "5976393" "5981305" "6010831" "6068939" "6189208" "2001/0006455").PN.	USPAT	2004/09/16 08:19
3	5	("3486223" "4208005" "4314870" "4345371" "4582975").PN.	USPAT	2004/09/16 08:22
4	81	IC near mounting and (228/123.1, 156/295 , 228/180.22 , 257/E21.503).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/16 08:32
5	3	("4249299" "4835847" "5045914").PN.	USPAT	2004/09/16 08:36
6	11	("2261015" "3382564" "3576969" "3650454" "3699640" "3700156" "3731867" "3883945" "3990863" "4295596" "4528746").PN.	USPAT	2004/09/16 08:36
-	2	6510607.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/09/15 10:15
-	17	(5793114, 5619017, 5891808, 5612514, 4380042, 4331740, 4331740, "4312926").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/09/15 17:27
-	863	IC and substrate and lead near connecting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/09/16 08:32
-	6	IC and substrate and lead near connecting and 29/832.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/09/15 17:30
-	74	IC and substrate and lead near connecting and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/09/15 17:38

-	7	("4862245" "4948645" "4994411" "4997517" "5041015" "5086018" "5108553").PN.	USPAT	2004/09/15 17:33
-	49	4948645.URPN.	USPAT	2004/09/15 17:35
-	16	("4684975" "4796078" "4862245" "4948645" "4994411" "4997517" "5041015" "5086018" "5089876" "5108553" "5151559" "5214845" "5221642" "5256903" "5277232" "5448450").PN.	USPAT	2004/09/15 17:36
-	257	IC and pcb and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:43
-	101	IC near lead and assembly and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:50
-	10	("4308339" "4771330" "4800419" "4842662" "4933741" "4965702" "4972253" "5023202" "5051813" "5300481").PN.	USPAT	2004/09/15 17:44
-	8	("3909838" "4803544" "4829403" "4859632" "5122858" "5213748" "5473512" "5477008").PN.	USPAT	2004/09/15 17:46
-	23	("3902148" "4050618" "4054238" "4224637" "4271426" "4331831" "4380042" "4514750" "4531044" "4584627" "4642419" "4725692" "4759771" "4814855" "4862246" "4920074" "4980802" "4982265" "4985663" "5018005" "5064706" "5121300" "5137479").PN.	USPAT	2004/09/15 17:48
-	24	("4333966" "4401767" "4436785" "4459166" "4463030" "4652465" "4670188" "4749120" "4855102" "4859241" "5194128" "5196371" "5286927" "5477419" "5714252" "5832595" "5860212" "5882722" "5918364" "5976393" "5981305" "6010831" "6068939" "6189208" "2001/0006455").PN.	USPAT	2004/09/15 17:55

	Title	Current OR
1	Device for dismounting integrated circuit devices	29/743
2	Methods and apparatus for bonding an article to a metallized substrate	228/180.21
3	Integrated-circuit block extraction tool	29/764
4	Method for transferring and joining beam leaded chips	228/176
5	VACUUM DIE SENSOR APPARATUS AND METHOD FOR A SEMICONDUCTOR DIE BONDING MACHINE	228/6.2
6	BONDING HEAD FOR BONDING BEAM LEADED DEVICES TO A SUBSTRATE	228/6.2
7	COMPLIANT BONDING	228/106
8	DEVICE FOR BONDING WITH A COMPLIANT MEDIUM	228/1.1

	Current XRef
1	219/229; 228/264; 228/55; 29/764
2	228/234.1; 228/264; 257/E21.511
3	219/230; 219/85.16; 228/264; 228/51; 29/278; 29/739
4	228/180.21; 228/234.1; 29/827; 29/840
5	228/10; 29/714; 29/827; 29/833
6	228/3.1; 228/45; 29/827
7	228/4.1; 228/5.5; 228/6.2; 269/266; 29/827
8	156/73.1; 228/106; 228/110.1; 228/180.21; 228/234.1; 228/5.5; 269/21; 269/285; 29/827

	Title	Current OR
9	SOLDER REFLOW DEVICE	219/221
10	Soldering apparatus and method for microelectronic circuits	228/173.5
11	Soldering iron	219/221

	Current XRef
9	219/227; 219/237; 219/543; 219/85.16; 228/51; 228/6.2; 29/827; 29/840; 29/846; 338/308
10	219/230; 219/85.15; 228/180.21; 228/191; 228/199; 228/20.1; 228/4.1
11	219/238; 228/55